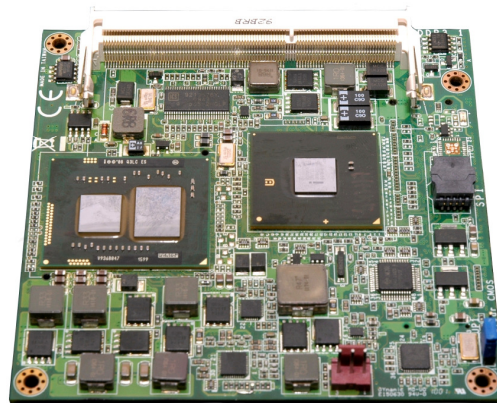


This Micro COM Express module delivers increased CPU performance and graphics in a small form factor. The pinout is type 2 compliant. The H6052 has options including a range of LV and ULV processors from Intel® Core™ i3, Core™ i5 and Core™ i7 family of processors and Mobile Intel® HM55 Express Chipset. The feature set includes all interfaces in the COM Express standard such as PCI, PCI Express, SDVO and LVDS as well as an onboard Intel® 82577 Gigabit Ethernet Controller. There is a H6052 version specified for Extended Temperature (-20 °C to +70 °C).



Target markets and applications

Where application requirements include compact size, high computing performance and advanced graphics the H6052 Micro COM Express Module on a custom-design carrier board is a strong option.

These are some ideas of applications suited for the H6052:



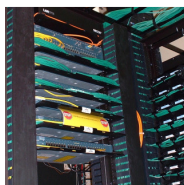
Medical



**Offshore/
Marine**



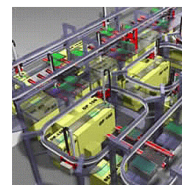
**Gaming/
Infotainment**



**Datacom/
Telecom**



Defence



**Industrial
Automation**

H6052 - Technical Specifications

Core Logic and Memory		Miscellaneous	
CPU options	Intel® Core™ i7 620LE, 2.0 GHz Intel® Core™ i7 620UE, 1.06 GHz Intel® Core™ i7 660UE, 1.33 GHz Intel® Core™ i7 610E, 2.53 GHz Intel® Core™ i5 520E, 2.40 GHz Intel® Core™ i3 330E, 2.13 GHz Intel® Celeron® P4505, 1.86 GHz Intel® Celeron® U3405, 1.07 GHz Some CPU options require minimum order quantities	Hardware Monitor	Yes
Chipset	Mobile Intel® HM55 Express Chipset	Watchdog Timer	Optional
Memory	1x DDR3 SO-DIMM up to 4 GB	CPU temp. sensor	Yes
Drives		CPU Fan Speed Meter	Yes
SATA	4x SATA	Onboard LED	Standby power
EIDE	JMB368 (UDMA6 support)	Over temp. protection	Yes
Standard Interfaces		OVP	Vcore, 2 phases
USB	8 USB 2.0 ports	Clear CMOS Jumper	Yes
Bus Interfaces		LAN Interface	
COM Express	Type 2 interface, fully compliant	Ethernet	1x Intel® 82577LM Gigabit Ethernet controller
PCI Express	1x PCI Express by 16, 4x PCI Express by 1	BIOS	
PCI Bus	4 ports	AMI BIOS	
Serial	I2C/SM Bus interface	Sound Interface	
Digital I/O	8 Bits	HD audio	
SDVO	Yes	Power Supply	
LPC	Low Pin Count bus for legacy interfaces	Power	+12V input, 5V SB
Flat Panel/ CRT Interface		Environment	
Graphics Engine	Latest generation Intel® integrated Graphics Media Accelerator for increased 3D and video acceleration performance	Ambient	0°-60°C (operating, standard) -20°-70°C (operating, Ext. temp version)
LCD Interface	LVDS 18/24 Bit, single/dual channel support	Temp.	-25°... 85°C (storage)
CRT Interface	1 port	Humidity	5 ... 95% (operating, non-condensing) 5 ... 95% (storage, non-condensing)
		Mechanical	
		Size	95mm x 95mm x 13mm

Accessories

- Fansink and COM Express heat spreader (only recommended for low power CPUs)
- H4113 - COM Express Reference Carrier Board
- H6052 COM Express Starter Kit

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HECTRONIC AB
Box 3002
SE-750 03 Uppsala
SWEDEN

Visitors address:
Fålhagsleden 59
Uppsala

Telephone: +46.18.660 700
Telefax: +46.18.660 701
E-mail: info@hectronic.se
Web: www.hectronic.se